

# HI 1005 Series

## High Frequency Multilayer Chip Inductors

### Features

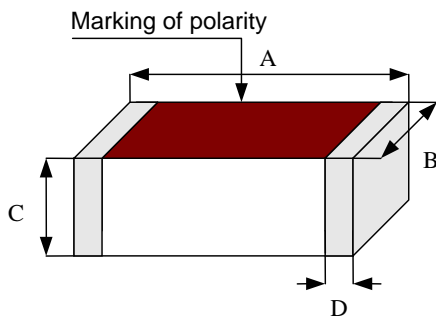
- ❖ Monolithic structure ensuring high performance and reliability.
- ❖ High frequency applications up to 6GHz.

### Applications

- ❖ RF modules for telecommunication systems including GSM, PCS, DECT, WLAN, Bluetooth, etc.



### Shape and Dimensions



Unit : mm (inch)

TYPE	EIA Code	A	B	C	D
1005	0402	1.00 ±0.10	0.50 ±0.10	0.50 ±0.10	0.23 ±0.10
		(.040 ±.004)	(.020 ±.004)	(.020 ±.004)	(.0092 ±.004)

\* Marking of polarity indicating the magnetic flux direction is taped upward.

### Part Number

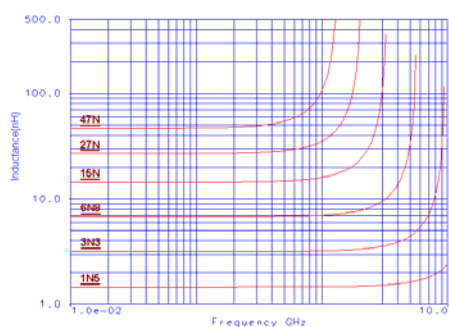
**HI 1005 - 1 C 4N7 □ □ □**

①      ②      ③ ④      ⑤      ⑥      ⑦      ⑧

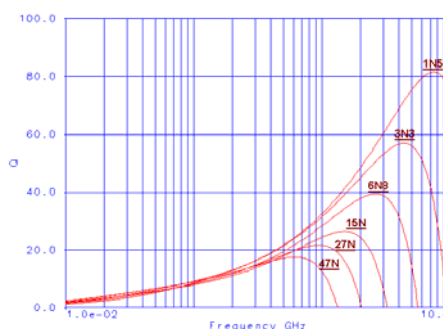
① Type	HI :High Frequency Inductors	② Dimensions ( L × W )	1.0 × 0.5 mm
③ Circuit	1 : Single	④ Material Code	B (lead-containing) C (lead-free)
⑤ Inductance	4N7=4.7nH 47N=47nH R10=100nH	⑥ Tolerance	S:±0.3nH, J:±5%,      K:±10%
⑦ Marking	M: With marking	⑧ Packaging	T: Tape & Reel B: Bulk

## Typical Electrical Characteristics

L vs. Frequency



Q vs. Frequency



## Specifications

Part Number	Inductance (nH)	Q Min.	L/Q Freq. (MHz)	R <sub>DC</sub> (Ω) Max.	S.R.F. (MHz) Typ.	I <sub>DC</sub> (mA) Max.
HI1005-1_1N0_M_	1.0 ± 0.3	8	100	0.12	>15000	300
HI1005-1_1N2_M_	1.2 ± 0.3	8	100	0.12	>15000	300
HI1005-1_1N5_M_	1.5 ± 0.3	8	100	0.13	>15000	300
HI1005-1_1N8_M_	1.8 ± 0.3	8	100	0.14	14000	300
HI1005-1_2N2_M_	2.2 ± 0.3	8	100	0.16	12000	300
HI1005-1_2N7_M_	2.7 ± 0.3	8	100	0.17	9500	300
HI1005-1_3N3_M_	3.3 ± 0.3 or ± 10%	8	100	0.19	8500	300
HI1005-1_3N9_M_	3.9 ± 0.3 or ± 10%	8	100	0.22	7000	300
HI1005-1_4N7_M_	4.7 ± 0.3 or ± 10%	8	100	0.24	6000	300
HI1005-1_5N6_M_	5.6 ± 0.3 or ± 10%	8	100	0.27	5400	300
HI1005-1_6N8_M_	6.8 ± 5% or ± 10%	8	100	0.32	5000	250
HI1005-1_8N2_M_	8.2 ± 5% or ± 10%	8	100	0.40	4600	250
HI1005-1_10N_M_	10 ± 5% or ± 10%	8	100	0.45	3700	250
HI1005-1_12N_M_	12 ± 5% or ± 10%	8	100	0.50	3200	250
HI1005-1_15N_M_	15 ± 5% or ± 10%	8	100	0.60	3100	250
HI1005-1_18N_M_	18 ± 5% or ± 10%	8	100	0.65	2900	200
HI1005-1_22N_M_	22 ± 5% or ± 10%	8	100	0.80	2100	200
HI1005-1_27N_M_	27 ± 5% or ± 10%	8	100	0.90	1900	200
HI1005-1_33N_M_	33 ± 5% or ± 10%	8	100	1.00	1600	200
HI1005-1_39N_M_	39 ± 5% or ± 10%	8	100	1.20	1400	150
HI1005-1_47N_M_	47 ± 5% or ± 10%	8	100	1.30	1200	150
HI1005-1_56N_M_	56 ± 5% or ± 10%	8	100	2.00	1100	150
HI1005-1_68N_M_	68 ± 5% or ± 10%	8	100	2.20	1000	100
HI1005-1_82N_M_	82 ± 5% or ± 10%	8	100	2.50	900	100
HI1005-1_R10_M_	100 ± 5% or ± 10%	8	100	2.50	850	100
HI1005-1_R12_M_	120 ± 5% or ± 10%	8	100	2.50	750	100

Operating Temperature Range : -40 ~ +100 °C

Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH

Storage Period: 12 months max.

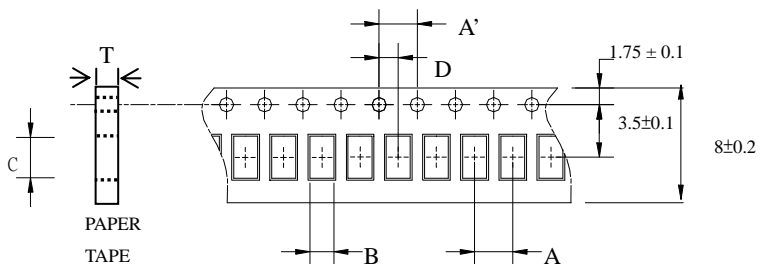
Test Method : L and Q	: HP 4291B (+16192A)
S.R.F. (Self Resonant Frequency)	: HP 8722D
R <sub>DC</sub> (DC Resistance)	: HP 4338B
I <sub>DC</sub> (Rated Current)	: HP 4284A

## Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

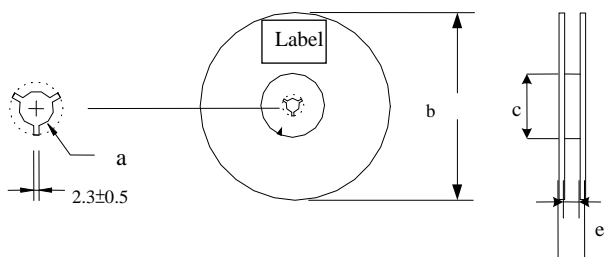
## Taping Specifications

### ❖Tape Dimensions (Unit: mm) & Quantity



### ❖Reel Dimensions (Unit: mm)

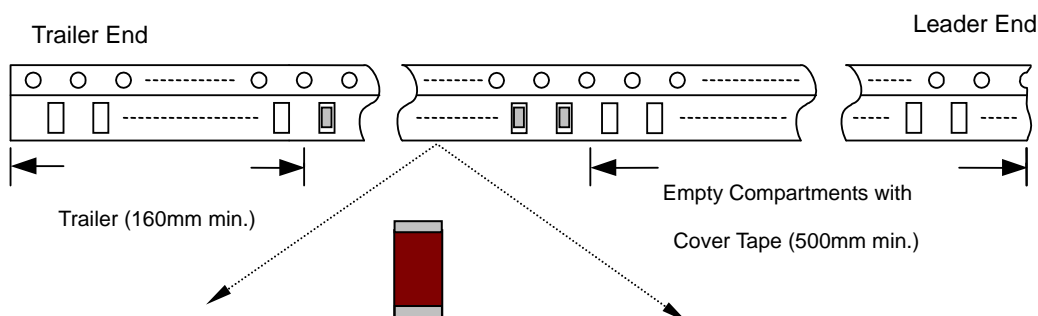
Type	A	A'	B	C	D	T	Quantity/ reel	Tape material
HI1005	2.0±0.05	4.0±0.1	0.62±0.03	1.15±0.03	2.0±0.05	0.60±0.03	10,000 pcs	Paper



Label: Customer's Name, ACX P/N,  
Q'ty, Date, ACX Corp.

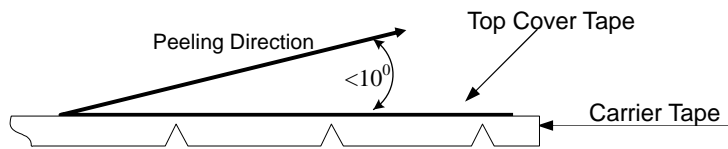
Type	a	b	c	d	e
HI1005	13.5±0.5	178±1	60±1	1.2±0.2	9.0±0.3

### ❖Leader / Trailer Tape (Unit: mm)



❖ **Peel-off Force**

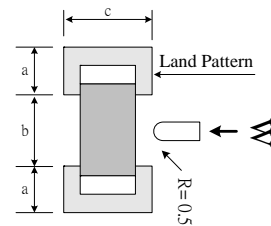
Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of  $300 \pm 10$  mm/min .



**Notes**

❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

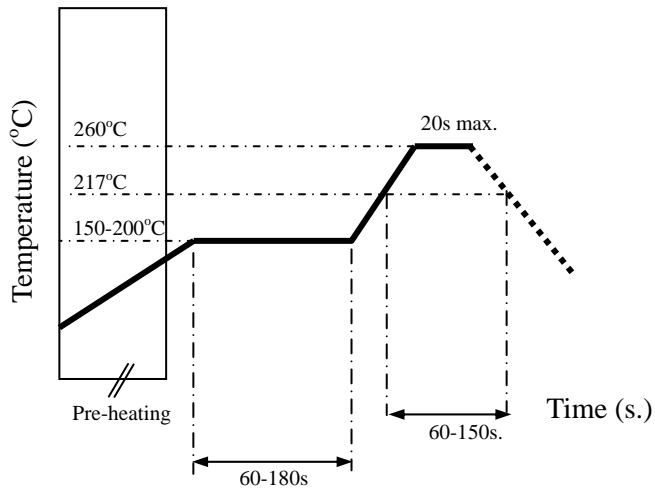
## Mechanical & Environmental Characteristics

tem	Requirements	Procedure										
Solderability	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>More than 95% of the terminal electrode shall be covered with new solder.</li> <li>L : within <math>\pm 10\%</math></li> <li>Q : within <math>\pm 20\%</math></li> </ol>	<ol style="list-style-type: none"> <li>Preheat : <math>120\pm 20^{\circ}\text{C}</math> for <math>\geq 1</math> min</li> <li>Solder : <math>245\pm 5^{\circ}\text{C}</math> for <math>5\pm 1</math> sec</li> </ol>										
Termination Adhesion (Flexure Strength)	<ol style="list-style-type: none"> <li>No apparent damage</li> </ol>	 <table border="1" data-bbox="1300 537 1452 772"> <thead> <tr> <th>Type</th> <th>HI1005</th> </tr> </thead> <tbody> <tr> <td>a (mm)</td> <td>0.6</td> </tr> <tr> <td>b (mm)</td> <td>0.5</td> </tr> <tr> <td>c (mm)</td> <td>0.6</td> </tr> <tr> <td>W (kgf)</td> <td>0.75</td> </tr> </tbody> </table>	Type	HI1005	a (mm)	0.6	b (mm)	0.5	c (mm)	0.6	W (kgf)	0.75
Type	HI1005											
a (mm)	0.6											
b (mm)	0.5											
c (mm)	0.6											
W (kgf)	0.75											
Solder Heat Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>More than 95% of the terminal electrode shall be covered with new solder.</li> </ol>	<ol style="list-style-type: none"> <li>Preheat : <math>120\pm 20^{\circ}\text{C}</math> for <math>\geq 1</math> min</li> <li>Solder : <math>260\pm 5^{\circ}\text{C}</math> for <math>10\pm 1</math> sec</li> </ol>										
Heat/ Humidity Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>L : within <math>\pm 10\%</math></li> <li>Q: within <math>\pm 20\%</math></li> <li>Fulfill the electrical specification</li> </ol>	<ol style="list-style-type: none"> <li>Temperature : <math>85 \pm 2^{\circ}\text{C}</math></li> <li>Humidity : 80%~85% RH</li> <li>Applied current : rated current</li> <li>Duration : <math>500 \pm 24</math> hours</li> <li>Recovery : 1-2hr</li> </ol>										
Thermal Shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>L : within <math>\pm 10\%</math></li> <li>Q: within <math>\pm 20\%</math></li> <li>Fulfill the electrical specification</li> </ol>	<ol style="list-style-type: none"> <li>One cycle/step 1 : <math>125 \pm 5^{\circ}\text{C}</math> for 30 min step 2 : <math>-40 \pm 3^{\circ}\text{C}</math> for 30 min</li> <li>No. of cycles : 100</li> <li>Recovery:1-2 hrs</li> </ol>										
Low Temperature Resistance	<ol style="list-style-type: none"> <li>No apparent damage</li> <li>L : within <math>\pm 10\%</math></li> <li>Q: within <math>\pm 20\%</math></li> <li>Fulfill the electrical specification</li> </ol>	<ol style="list-style-type: none"> <li>Temperature : <math>-40 \pm 5^{\circ}\text{C}</math></li> <li>Duration : <math>500 \pm 24</math> hours</li> <li>Recovery : 1-2hr</li> </ol>										

## Soldering Conditions

### ❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



## Notes

❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

### **Advanced Ceramic X Corp.**

16 Tzu Chiang Road, Hsinchu Industrial District Hsinchu Hsien 303, Taiwan

TEL:886-3-5987008 FAX:886-3-5987001

E-mail: [acx@acxc.com.tw](mailto:acx@acxc.com.tw)

<http://www.acxc.com.tw>